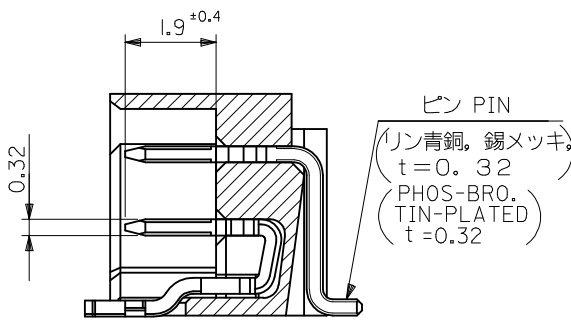
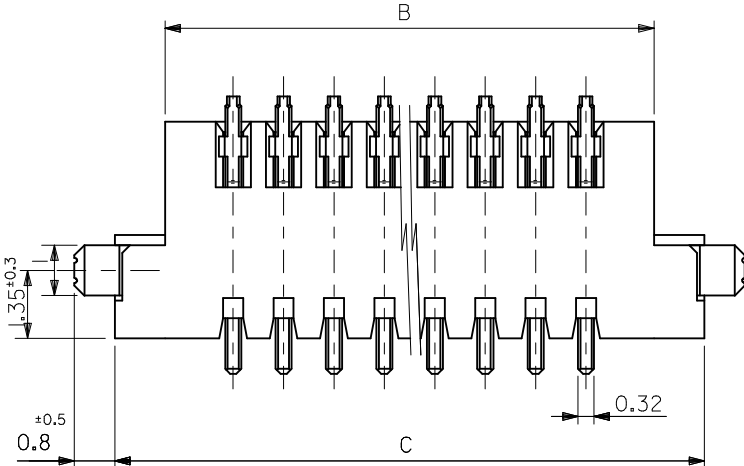


パターン参考寸法 (マウント面)  
RECOMMENDED DIM. FOR P.C.BOARD  
MOUNTING PATTERN (REF.)



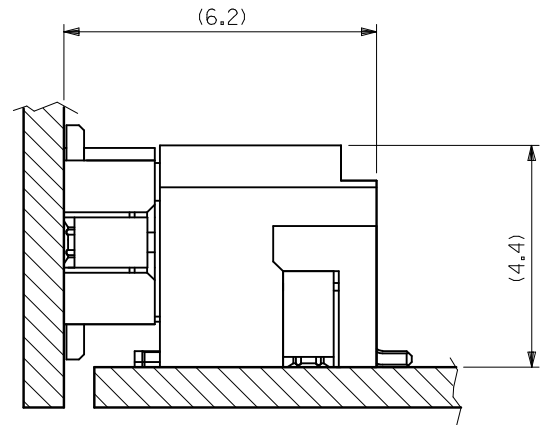
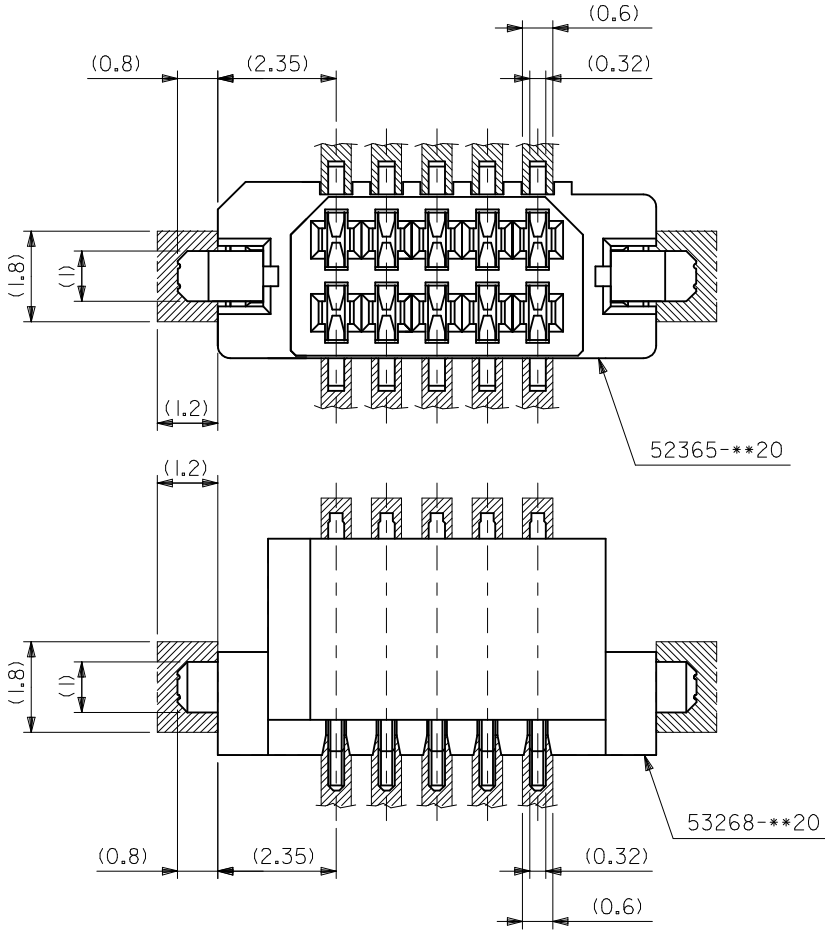
SECT.F-F

18.7	16.7	14	53268-3020	30
15.7	13.7	11	53268-2420	24
12.7	10.7	8	53268-1820	18
6.7	4.7	2	53268-0620	6
C	B	A	MATERIAL NO.	極数 CIRCUIT
			MODEL NO.	53268-***20

注記 NOTES.

1. 嵌合相手 : 52365-\*\*\*10 , 52365-\*\*\*20  
MATES WITH : 52365-\*\*\*10 , 52365-\*\*\*20
  2. ハウジングの底面 G からの金具及びターミナル半田付面のズレ量は  
上方向 0.1 MAX. 下方向 0.15 MAX. とする。  
MISALIGNMENT OF SOLDER TAIL TIP AND FITTING NAIL  
FROM G  
: UPPER DIRECTION 0.1mm MAX.  
: LOWER DIRECTION 0.15mm MAX.
- △ パターンハクリ止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B.  
PATTERN.

REVISED EC NO. J2009-0666 DRWN: MAKURAA 2008/09/25 CHKD: T. HARYAMA 2008/09/25 APPR: NUKITA 2008/09/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)		
		10 OVER 30 UNDER	±0.25	CHECKED BY M. FUKUSHIMA	DATE '92/8/4	MOLEX INCORPORATED		
		30 OVER	±0.3	APPROVED BY M. ENOMOTO	DATE '92/8/4	DOCUMENT NO. SD-53268-011		
REV		ANGULAR	±3 °	MATERIAL NO.	SEE TABLE			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



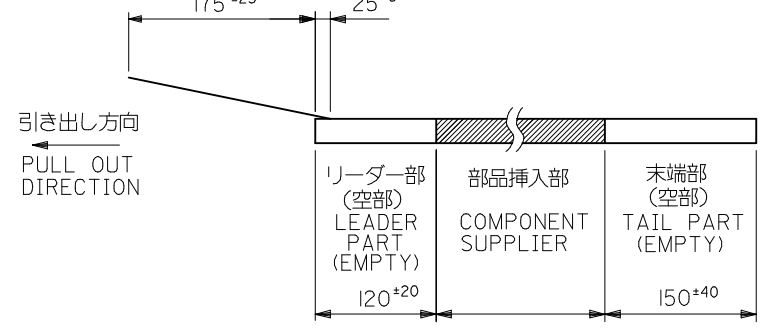
基板取付推奨レイアウト  
RECOMMENDED P.C.BOARD LAYOUT

MODEL NO. 53268-\*\*20

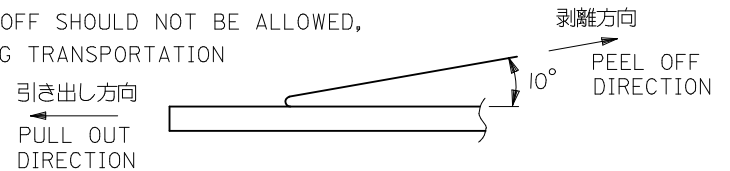
REVISED EC NO: J2009-0666 DRWN: KAKURAA 2008/09/25 CHKD: T. HARIYAMA 2008/09/25 APPR: NUKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)			
	10 OVER 30 UNDER	± ---	CHECKED BY M. FUKUSHIMA	DATE '92/8/4				
	30 OVER	± ---	APPROVED BY M. ENOMOTO	DATE '92/8/4	MOLEX INCORPORATED			
	ANGULAR ± --- °		MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-53268-011		2 OF 2		

注記 NOTES

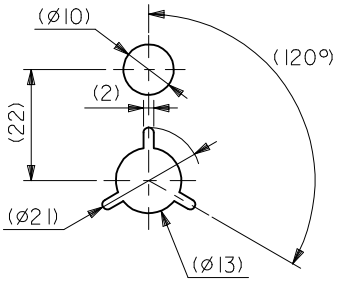
1. 梱包数量: 1000個/リール NUMBER OF CONNECTORS: 1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH  
 トップテープ TOP TAPE  
 リーダー部 LEADER PART 未接着部 NON-BONDED PART



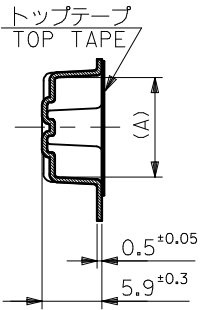
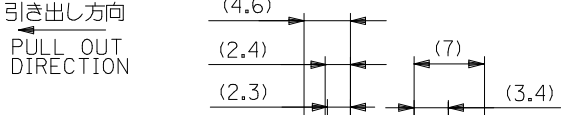
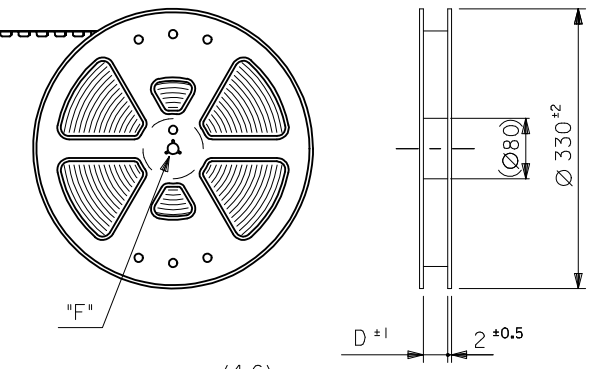
3. トップテープの剥離強度: (剥離方向は下図参照)  
 60gf MAX. 尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)  
 PEELING OFF FORCE OF TOP TAPE  
 60gf MAX. (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION



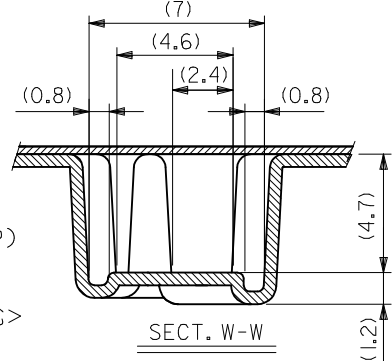
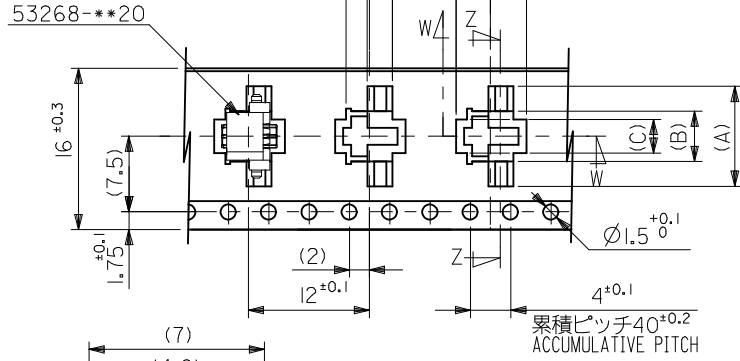
引き出し方向  
PULL OUT  
DIRECTION



DETAIL "F"



SECT. Z-Z

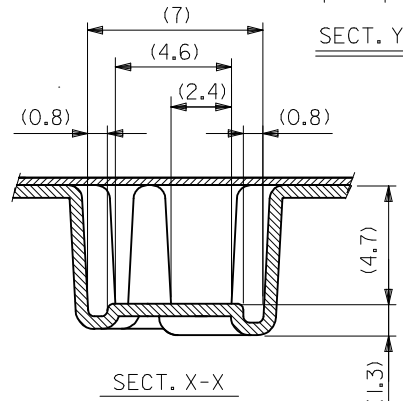
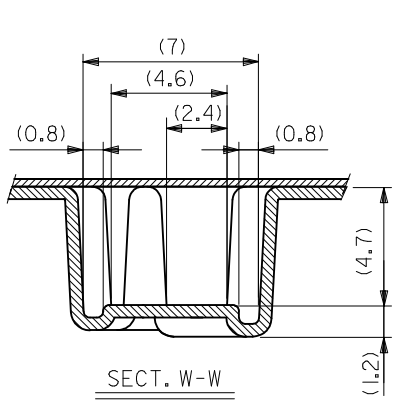
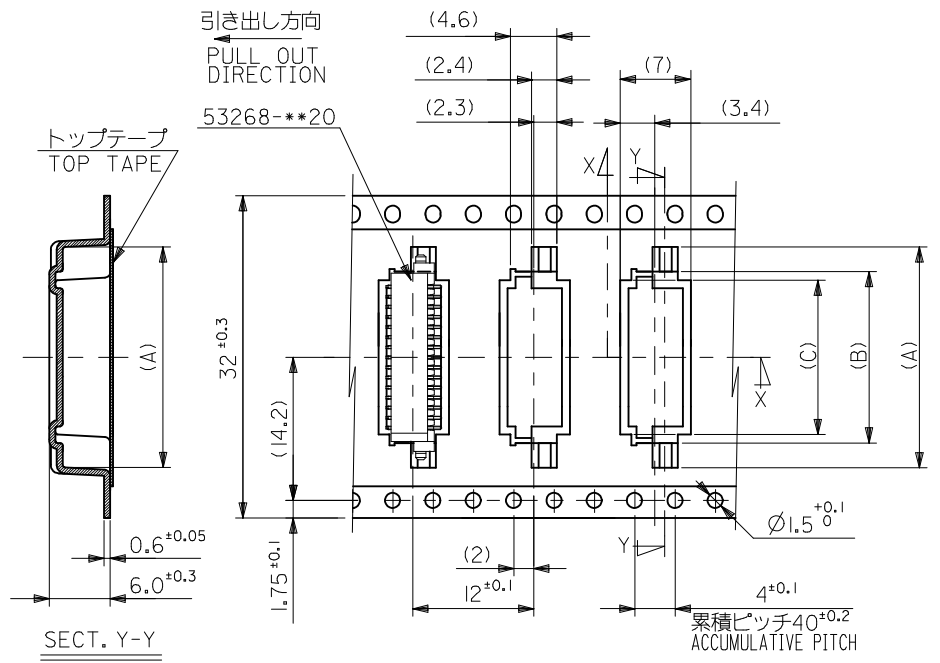
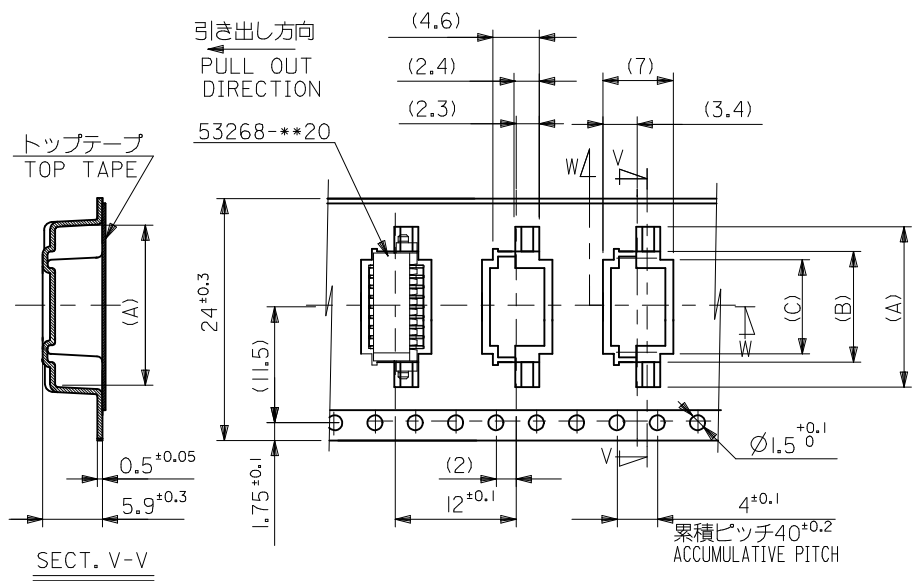


SECT. W-W

4. 材料  
 キャリアテープ: ポリプロピレン (PP)  
 トップテープ: PET, PE, PEF  
 リール: ポリスチレン (PS)  
 <リサイクル材を含む>  
 MATERIAL  
 CARRIER TAPE: POLYPROPYLENE  
 TOP TAPE: PET, PE, PEF  
 REEL: POLYSTYREN(PS)  
 <RECYCLE MATERIAL  
 CONTAINED>

16	17.5	3.1	5	9.9	53268-0691	6
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
					MODEL NO.	53268-***91

REVISED EC NO: J2009-0666 DRWN: MAKURAA 2008/09/25 CHKD: T. HARUYAMA 2008/09/25 APPR: NUKITA 2008/09/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER ± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (1/2)			
		10 OVER 30 UNDER ± ---	CHECKED BY T. ITO	DATE '00/12/6	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	MOLEX INCORPORATED	
		30 OVER ± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-53268-012	SHEET NO. 1 OF 2		
ANGULAR ± --- °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								



32	33.5	15.15	17	21.9	53268-3091	30
		12.15	14	18.9	53268-2491	24
24	25.5	9.1	11	15.9	53268-1891	18
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-0666 DRWN: MAKURAA 2008/09/25 CHKD: T. HARUYAMA 2008/09/25 APPR: NUKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 53268-**-91
	10 UNDER	± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (2/2)		
	10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	APPROVED BY M. FUKUSHIMA '00/12/6		
	30 OVER	± ---	MATERIAL NO.		MOLEX INCORPORATED		
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO. SD-53268-012	SHEET NO. 2 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							